

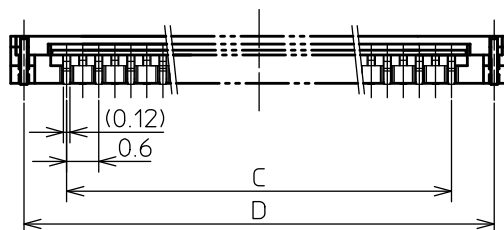
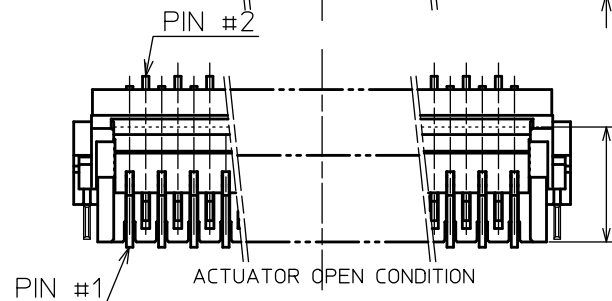
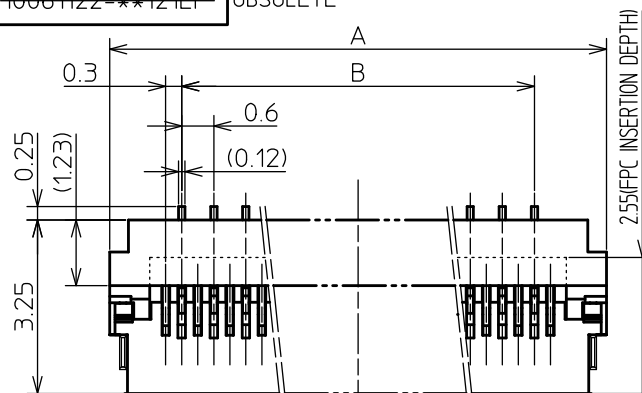
PDS: Rev :T STATUS:Released Printed: Apr 20, 2015

Printed: Apr 20, 2015

PRODUCT NO.

40061122-**-121LF

OBSOLETE



NOTE

1.MATERIAL

- 1)HOUSING:THERMOPLASTIC RESIN,UL94V-0,NATURAL
2)ACTUATOR:THERMOPLASTIC RESIN,UL94V-0,BLACK
3)CONTACT:COPPER ALLOY
4)FIXING TAB:COPPER ALLOY

2.FINISH

- 1)CONTACT:ALL OVER Ni (WITH Ni BARRIER)
(CONTACT AREA)Au
(SOLDER TAIL AREA)Au
2)FIXING TAB:ALL OVER Ni
Sn PLATING

3.CO-PLANARITY ± 0.08 MAX

4.THICKNESS OF A METAL MASK:0.1mm

5.FPC

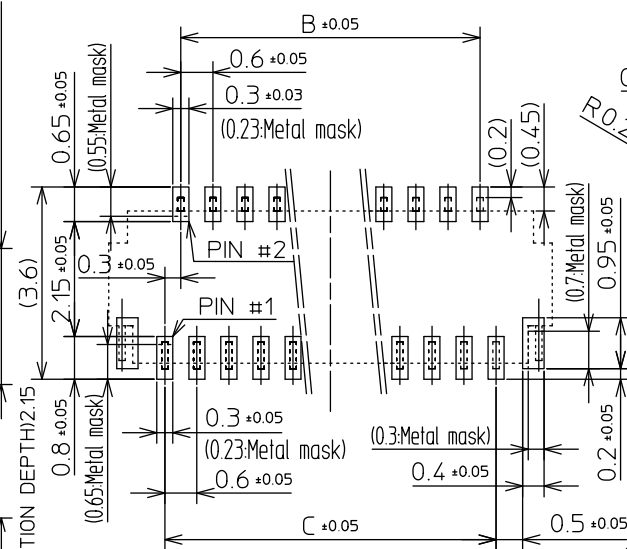
ADHESIVE METHOD OF SUPPORTING TAP SHALL BE HEAT CRIMPING
METHOD AND THERMOSETTING ADHESIVE MATERIAL SHALL BE USED.

6.PRODUCT

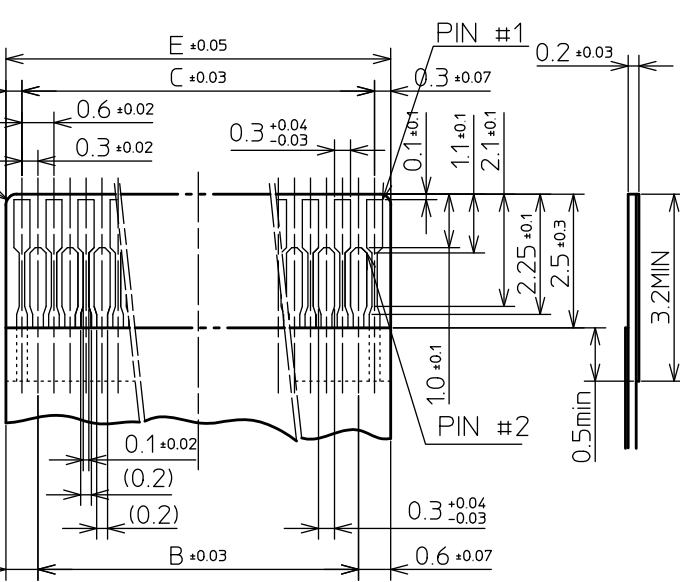
RECOMMENDED PCB LAYOUT AND FPC AREA THE SAME AS 10064555-**-2210ELF(YLL-UPPER CONTACT TYPE)

7.OTHER

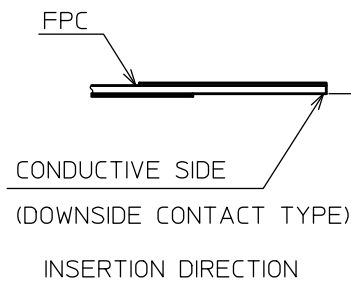
THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER
COUNTRY REGULATIONSAS DESCRIBED IN GS-22-008



RECOMMENDED PCB BOARD LAYOUT



RECOMMENDED FPC CONFIGURATION



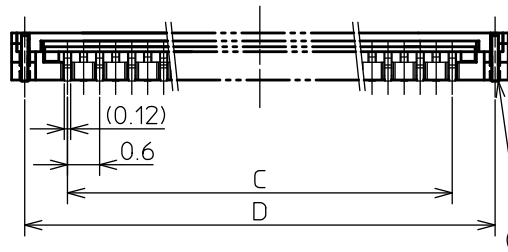
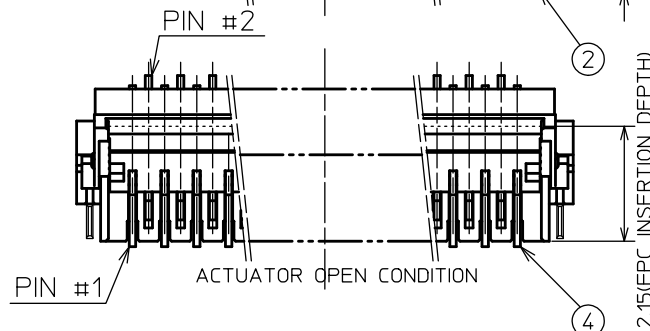
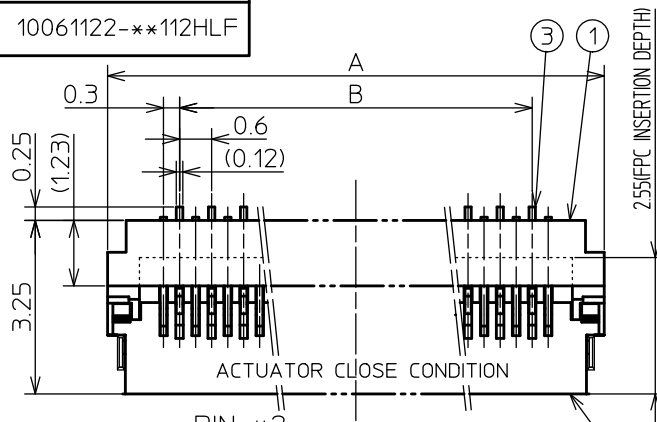
0.35(FPC INSERTION HEIGHT)

P/N	A	B	C	D	E	
40061122-45121LF	6.3	3.6	4.2	5.8	4.8	OBSOLETE
40061122-21121LF	8.1	5.4	6.0	7.6	6.6	OBSOLETE
40061122-23121LF	8.7	6.0	6.6	8.2	7.2	OBSOLETE
40061122-25121LF	9.3	6.6	7.2	8.8	7.8	OBSOLETE
40061122-33121LF	11.7	9.0	9.6	11.2	10.2	OBSOLETE
40061122-35121LF	12.3	9.6	10.2	11.8	10.8	OBSOLETE
40061122-37121LF	12.9	10.2	10.8	12.4	11.4	OBSOLETE
40061122-39121LF	13.5	10.8	11.4	13.0	12.0	OBSOLETE
40061122-41121LF	14.1	11.4	12.0	13.6	12.6	OBSOLETE
40061122-43121LF	14.7	12.0	12.6	14.2	13.2	OBSOLETE
40061122-45121LF	15.3	12.6	13.2	14.8	13.8	OBSOLETE

mat'l. code					surface		tolerance		projection		product family			CODE		
					ISO 1302		ISO 406		ISO 1101		587F			JP		
l/r	description		ec'n no	dr	date		tolerances unless otherwise specified					title			0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE	
G	REVISED		ELX-J-01245-1	T.I	2012-08-31											
F	REVISED		J11-0280	T.I	2011-12-14		angles		linear		± 0.2		MM			
E	REVISED		J10-0185	T.I	2010-7-6								scale			
D	REVISED		J10-0073	T.I	2010-5-17		dr		TISHISHITA		2012-08-31		FCI			
C	REVISED		J08-0430	K.O	2008-11-10		engr		H.Suzuki		2012-08-31		dwg no			
B	REVISED		J08-0189	K.O	2008-4-28		chr		M.Kajiura		2012-08-31		sheet of			
A	RELEASED		J07-0399	K.O	28/Sep/07		appd				2012-08-31		3 of 37			
sheet		revision										type		Product Customer Drawing		
index		sheet										Rev.		G		

PRODUCT NO.

10061122-**-112HLF



CONNECTOR

PARTS NAME	MATERIAL	QTY	REMARKS
1 HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK
2 ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL
3 CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA: Au SOLDER TAIL AREA: Au
4 CONTACT B	COPPER ALLOY	(n+1)/2	
5 FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni,Sn

NOTE

1.CO-PLANARITY:0.08mmMAX

2.THICKNESS OF A METAL MASK:0.1mm

3.FPC

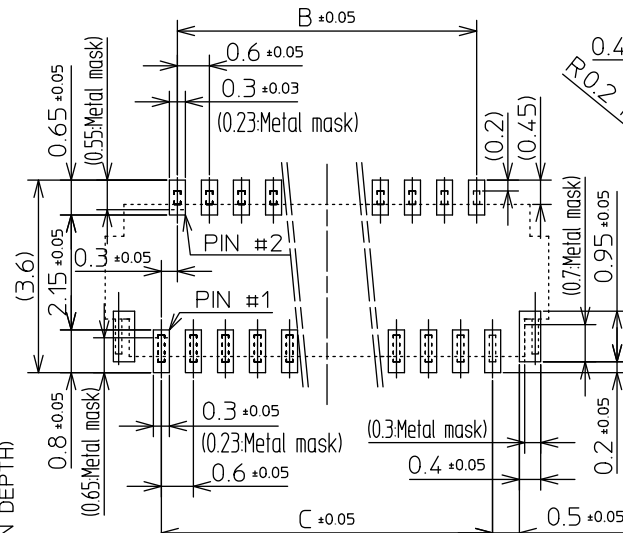
Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.

4.PRODUCT

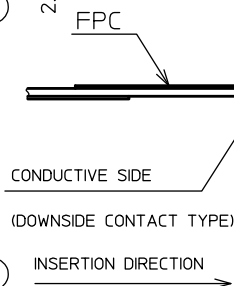
Recommended PCB layout and FPC area the same as 10064555-**-2110*LF(YLL-Upper contact type)

5.OTHER

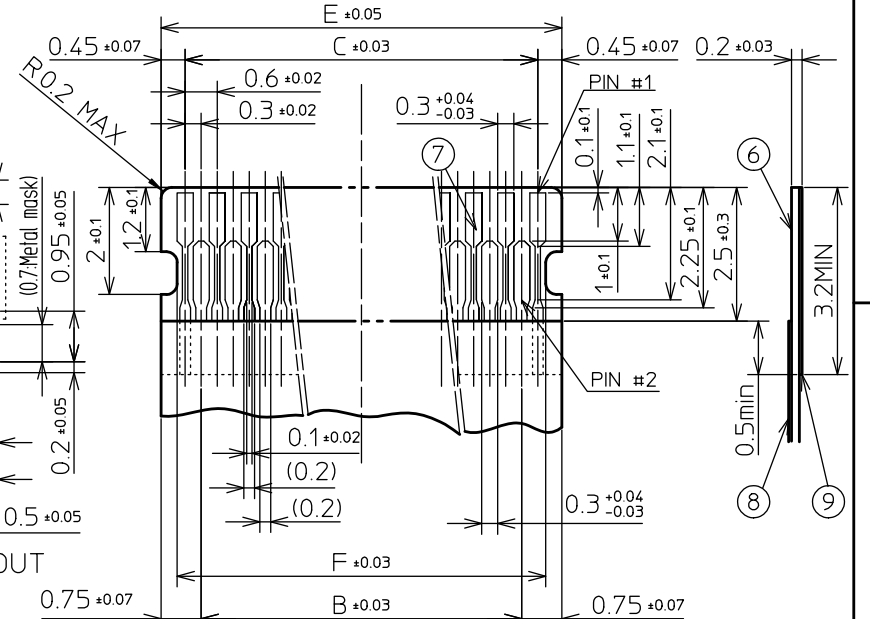
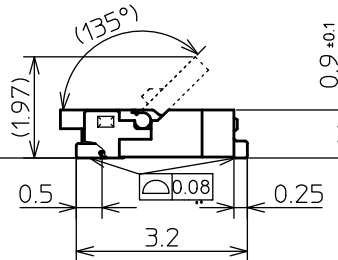
This product meets European Union Directives and other country regulation as described in GS-22-008



RECOMMENDED PC BOARD LAYOUT



0.35(FPC) INSERTION HEIGHT



RECOMMENDED FPC CONFIGURATION

FPC

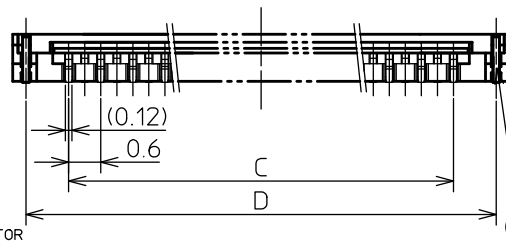
PARTS NAME	MATERIAL	QTY	REMARKS
6 BASE FILM	POLYAMIDE	1	
7 CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni 4~12 μm, Au 0.05~0.15 μm
8 OVERLAY	POLYAMIDE	1	
9 STIFFENER	POLYAMIDE	1	

n:NO OF CONTACT

P/N	A	B	C	D	E	F
10061122-13112HLF	5.7	3.0	3.6	5.2	4.5	3.9
10061122-15112HLF	6.3	3.6	4.2	5.8	5.1	4.5
10061122-17112HLF	6.9	4.2	4.8	6.4	5.7	5.1
10061122-21112HLF	8.1	5.4	6.0	7.6	6.9	6.3
10061122-23112HLF	8.7	6.0	6.6	8.2	7.5	6.9
10061122-25112HLF	9.3	6.6	7.2	8.8	8.1	7.5

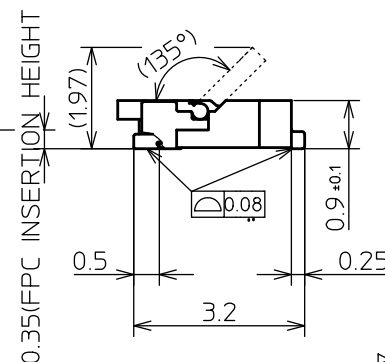
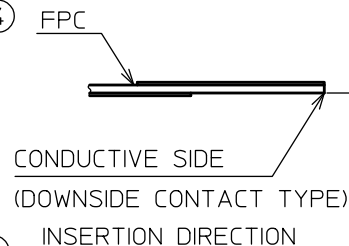
*For the corresponding position, please make an inquire to sales person in our company.

mat'l. code					surface ☒		tolerance ☒		projection		product family 587F (YLL-D)		CODE JP		
					ISO 1302		ISO 406 ISO 1101								
lfr	description	ecn no	dr	date	tolerances unless otherwise specified							title			
A	Released	J10-0185	T.I.	2010-07-06	angles	linear	±0.2				0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE				
					±2'				scale						
					dr	T.ISHISHITA	2010-07-06				dwg no		sheet of		size
					enrg						10061122		4 of 7		A3
					chr		Y Kameda 2010-07-06								
					appd	M.Kajiura	2010-07-06				type		Product	Customer	Drawing
sheet index	revision				sheet										Rev. A



	PARTS NAME	MATERIAL	QTY	REMARKS
1	HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0.COLOR BLACK
2	ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0.COLOR NATURAL
3	CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni WITH NI BARRIER
4	CONTACT B	COPPER ALLOY	(n+1)/2	CONTACT AREA Au SOLDER TAIL AREA: Au
5	FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni Sn

This product meets European Union Directives and other country regulation
as described in GS-22-008



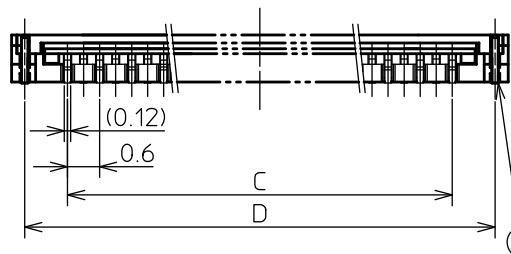
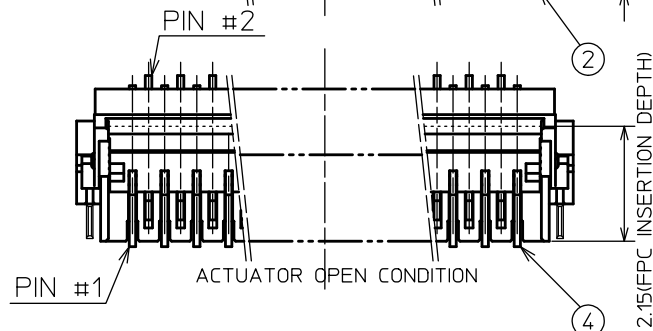
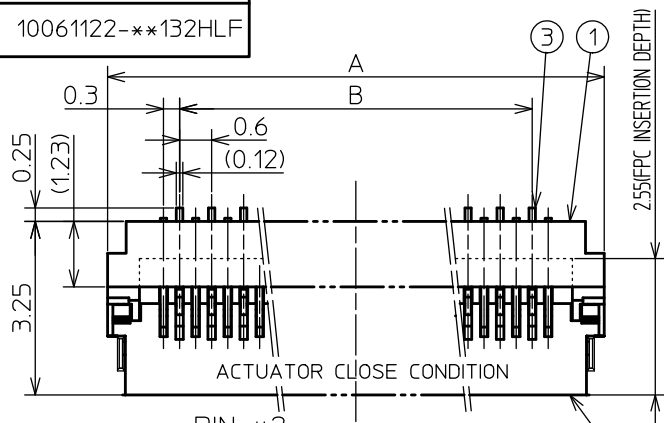
P/N	A	B	C	D	E
10061122-15122HLF	6.3	3.6	4.2	5.8	4.8
10061122-21122HLF	8.1	5.4	6.0	7.6	6.6
10061122-23122HLF	8.7	6.0	6.6	8.2	7.2
10061122-25122HLF	9.3	6.6	7.2	8.8	7.8

*For the corresponding position, please make an inquire to sales person in our company.

[illegible]

PRODUCT NO.

10061122-**-132HLF



CONNECTOR

PARTS NAME	MATERIAL	QTY	REMARKS
1 HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK
2 ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL
3 CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA: Au SOLDER TAIL AREA: Au
4 CONTACT B	COPPER ALLOY	(n+1)/2	[PLATING] ALL OVER Ni,Sn
5 FIXING TAB	COPPER ALLOY	2	

NOTE

- 1.CO-PLANARITY:0.08mmMAX
2.THICKNESS OF A METAL MASK:0.1mm
3.FPC

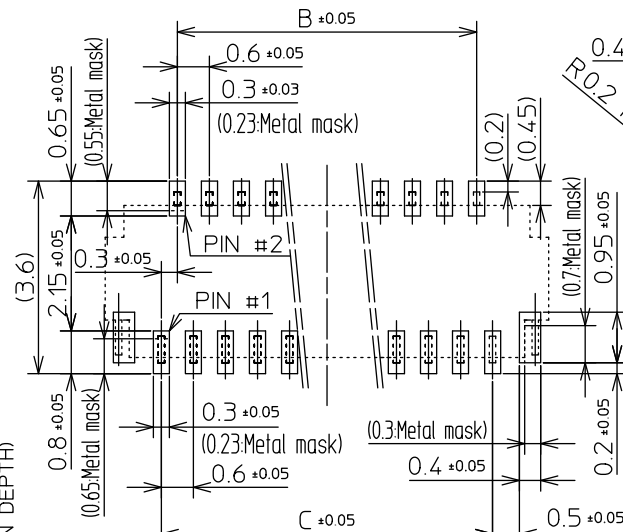
Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.

4.PRODUCT

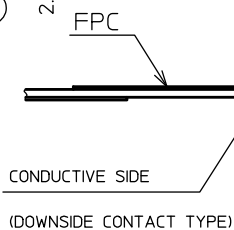
Recommended PCB layout and FPC area the same as 10064555-**-2110*LF(YLL-Upper contact type)

5.OTHER

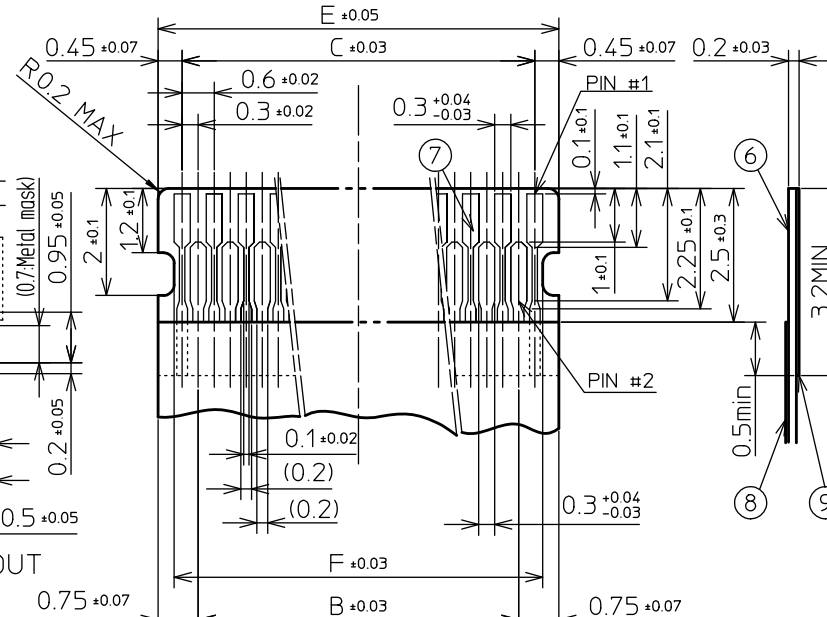
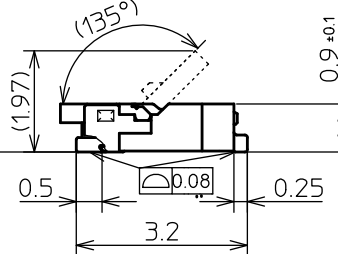
This product meets European Union Directives and other country regulation as described in GS-22-008



RECOMMENDED PC BOARD LAYOUT



0.35(FPC) INSERTION HEIGHT



RECOMMENDED FPC CONFIGURATION

FPC

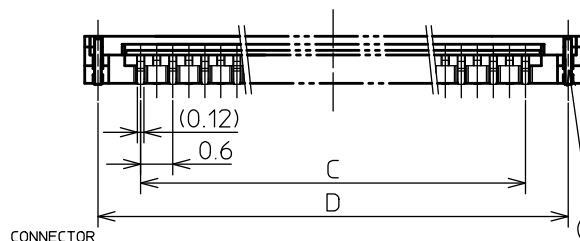
PARTS NAME	MATERIAL	QTY	REMARKS
6 BASE FILM	POLYAMIDE	1	
7 CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni 4~12μm, Au 0.05~0.15μm
8 OVERLAY	POLYAMIDE	1	
9 STIFFENER	POLYAMIDE	1	

n: NO OF CONTACT

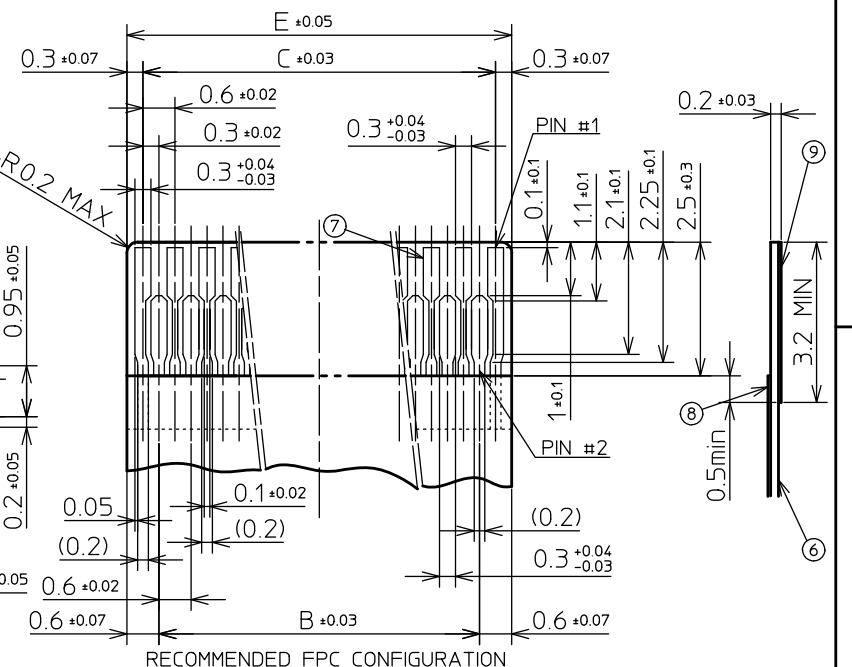
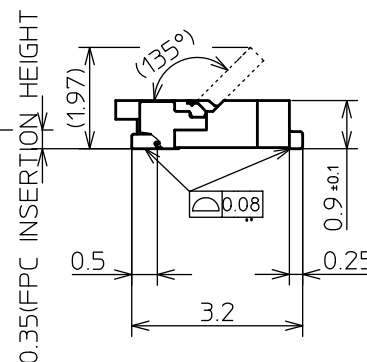
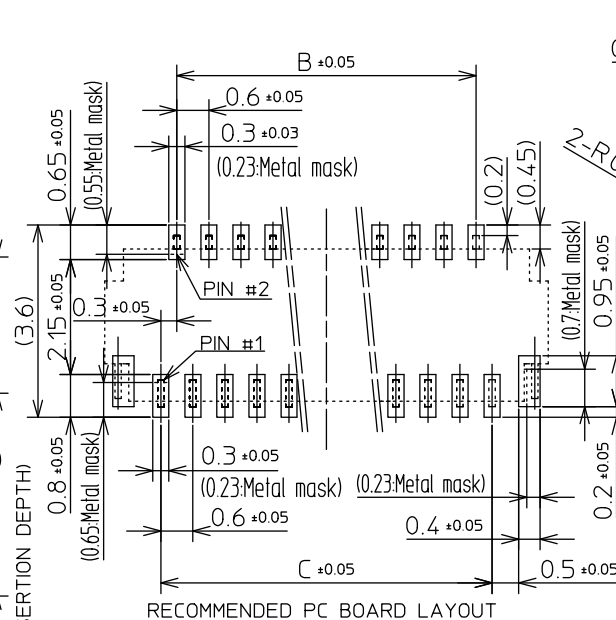
P/N	A	B	C	D	E	F
10061122-27132HLF	9.9	7.2	7.8	9.4	8.7	8.1
10061122-29132HLF	10.5	7.8	8.4	10.0	9.3	8.7
10061122-33132HLF	11.7	9.0	9.6	11.2	10.5	9.9
10061122-35132HLF	12.3	9.6	10.2	11.8	11.1	10.5
10061122-39132HLF	13.5	10.8	11.4	13.0	12.3	11.7
10061122-41132HLF	14.1	11.4	12.0	13.6	12.9	12.3
10061122-45132HLF	15.3	12.6	13.2	14.8	14.1	13.5

*For the corresponding position, please make an inquire to sales person in our company.

mat'l. code					surface ISO 1302		tolerance ISO 406 ISO 1101		projection 		product family 587F (YLL-D)				CODE JP		
ltr	description		ecn no	dr	date		tolerances unless otherwise specified					title					
A	Released		J10-0185	T.I	2010-07-06		angles		linear	±0.2				0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE			
B	Revised		J10-0268	T.I	2010-10-12												
C	Revised		ELX-J-012415-1	T.I	2012-08-31		± 2'										
					dr	T.ISHISHITA		2012-08-31				dwg no		sheet of		size	
				enrg	H Suzuki		2012-08-31		10061122			6 of 7		A3			
				chr	MKajiura		2012-08-31										
				appd													
sheet index		revision sheet														Rev. C	



NOTE	nNO OF CONTACT
1.CO-PLANARITY:0.08mmMAX	
2.THICKNESS OF A METAL MASK:0.1mm	
3.FPC	
Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.	
4.PRODUCT	
Recommended PCB layout and FPC area the same as 10064555-**2110*LF(YLL-Upper contact type)	
5.OTHER	
This product meets European Union Directives and other country regulation as described in GS-22-008	



FPC				
	PARTS NAME	MATERIAL	QTY	REMARKS
6	BASE FILM	POLYAMDE	1	
7	CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni 4~12μm Au 0.05~0.15μm
8	OVERLAY	POLYAMIDE	1	
9	STIFFENER	POLYAMIDE	1	

P/N	A	B	C	D	E
10061122-33142HLF	11.7	9.0	9.6	11.2	10.2
10061122-39142HLF	13.5	10.8	11.4	13.0	12.0
10061122-41142HLF	14.1	11.4	12.0	13.6	12.6
10061122-43142HLF	14.7	12.0	12.6	14.2	13.2
10061122-45142HLF	15.3	12.6	13.2	14.8	13.8
10061122-51142HLF	17.1	14.4	15.0	16.6	15.6

*For the corresponding position, please make an inquire to sales person in our company.

mat'l. code					surface ISO 1302 ✓		tolerance ISO 406 ISO 1101		projection 		product family 587F (YLL-D)			CODE JP	
lfr	description	ecn no	dr	date	tolerances unless otherwise specified					title					
A	Released	J10-0185	T.I	2010-07-06	angles	linear	± 0.2			0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE					
B	Revised	ELX-J-01245-1	T.I	2012-08-31											
C	Revised	ELX-J-14161-1	T.I	2013-03-05			± 2°								
					dr	T.ISHISHITA		2013-03-05			dwg no		sheet of		size
					enrg						10061122		7 of 7		A3
					chr	H.Suzuki		2013-03-05			type Product Customer Drawing				
					apnd	N.Sasame		2013-03-05							
sheet index	revision sheet														Rev. C